

Zytel® HTN high performance polyamide resins feature high retention of properties upon exposure to elevated temperature, to high moisture, and to harsh chemical environments. Polymer families and grades of Zytel® HTN are tailored to optimize performance as well as processability.

Typical applications with Zytel® HTN include demanding applications in the automotive, electrical and electronics, domestic appliances, and construction industries.

Zytel® HTNFR52G30BL NC010 is a 30% glass reinforced, flame retardant, lubricated high performance polyamide resin that has been developed for connector applications.

Product information

Resin Identification Part Marking Code Part Marking Code ISO designation	PA6T/66-GF30Ff >PA6T/66-GF30F >PPA-GF30FR< ISO 16396-PA6T	ISO 1043 ISO 11469 SAE J1344 2),M1F1GNR,S10-120	
Rheological properties	dry/cond.		
Moulding shrinkage, parallel Moulding shrinkage, normal	0.3/- 0.8/-	% %	ISO 294-4, 2577 ISO 294-4, 2577
Typical mechanical properties	dry/cond.		
Tensile modulus Tensile stress at break, 5mm/min Tensile strain at break, 5mm/min Flexural modulus Flexural strength Charpy impact strength, 23°C Charpy impact strength, -30°C Charpy impact strength, -40°C Charpy notched impact strength, 23°C Charpy notched impact strength, -30°C Poisson's ratio	12000/11000 170/150 2/2 10500/- 250/220 50/30 50/40 40/- 11/- 11/- 0.33/0.34	MPa MPa % MPa kJ/m ² kJ/m ² kJ/m ² kJ/m ²	ISO 527-1/-2 ISO 527-1/-2 ISO 527-1/-2 ISO 178 ISO 179/1eU ISO 179/1eU ISO 179/1eU ISO 179/1eA ISO 179/1eA
Thermal properties Melting temperature, 10°C/min Melting temperature, first heat Glass transition temperature, 10°C/min Temperature of deflection under load, 1.8 MPa Temperature of deflection under load, 0.45 MPa Coeff. of linear therm. expansion, parallel, -40-23°C Coefficient of linear thermal expansion	dry/cond. 310/* 310/* 90/45 282/* 300/* 20/* 20/*	°C °C °C °C E-6/K E-6/K	ISO 11357-1/-3 ISO 11357-1/-3 ISO 11357-1/-3 ISO 75-1/-2 ISO 75-1/-2 ISO 11359-1/-2 ISO 11359-1/-2
(CLTE), parallel Coeff. of linear therm. expansion, parallel, 55-160°C Coeff. of linear therm. expansion, normal, -40-23°C Coefficient of linear thermal expansion (CLTE), normal Coeff. of linear therm. expansion, normal, 55-160°C RTI, electrical, 1.5mm	10/* 57/* 63/* 100/* 140	E-6/K E-6/K E-6/K °C	ISO 11359-1/-2 ISO 11359-1/-2 ISO 11359-1/-2 ISO 11359-1/-2 UL 746B

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°C UL 746B RTI, electrical, 3.0mm 140 °C RTI, impact, 1.5mm 120 UL 746B RTI, impact, 3.0mm 120 °C UL 746B RTI, strength, 1.5mm 120/*°C UL 746B RTI, strength, 3.0mm °C UL 746B 130 Flammability dry/cond. Burning Behav. at 1.5mm nom. thickn. V-0/* class IEC 60695-11-10 Thickness tested 1.5/* mm IEC 60695-11-10 **UL** recognition yes/* UL 94 V-0/* IEC 60695-11-10 Burning Behav. at thickness h class Thickness tested 3/* mm IEC 60695-11-10 **UL** recognition yes/* UI 94 IEC 60695-11-20 Burning Behav. 5V at thickness h 5VA/* class Thickness tested IEC 60695-11-20 1.5/* mm **UL** recognition ves/* UL 94 ISO 4589-1/-2 Oxygen index 42/* % Glow Wire Flammability Index, 0.75mm 960/-°C IEC 60695-2-12 °C Glow Wire Flammability Index, 1.5mm 960/-IEC 60695-2-12 °C Glow Wire Flammability Index, 3.0mm 960/-IEC 60695-2-12 Glow Wire Ignition Temperature, 0.75mm °C 925/-IEC 60695-2-13 Glow Wire Ignition Temperature, 1.5mm 925/-°C IEC 60695-2-13 960/-°C Glow Wire Ignition Temperature, 3.0mm IEC 60695-2-13 Glow Wire Temperature, No Flame, 3mm 960/-°C IEC 60335-1 **FMVSS Class** DNI ISO 3795 (FMVSS 302) Electrical properties dry/cond. Relative permittivity, 100Hz 3.5/-IEC 62631-2-1 Relative permittivity, 1MHz 3.3/-IEC 62631-2-1 50/-E-4 IEC 62631-2-1 Dissipation factor, 100Hz Dissipation factor, 1MHz 140/-F-4 IEC 62631-2-1 Volume resistivity >1E13/-Ohm.m IEC 62631-3-1 Electric strength 34/kV/mm IEC 60243-1 Comparative tracking index 525/-IEC 60112 Comparative tracking index, 23°C 1/-PLC UL 746A Comparative tracking index M 175/-IEC 60112 Physical/Other properties dry/cond. Humidity absorption, 2mm 1.3/*Sim. to ISO 62 % Water absorption, 2mm 3/* % Sim. to ISO 62 0.21^[1]/* Sim. to ISO 62 Water absorption, Immersion 24h % Density 1620/kg/m³ ISO 1183 [1]: 2mm thickness



VDA Properties	dry/cond.				
Odour	4.5		class		VDA 270
Fogging, F-value (refraction)	95/*	r	%		ISO 6452
Injection					
Drying Recommended		yes			
Drying Temperature		100	°C		
Drying Time, Dehumidified Dryer		6 - 8	h		
Processing Moisture Content		≤0.1			
Melt Temperature Optimum		325	-		
Min. melt temperature		320			
Max. melt temperature		330	-		
Min. mould temperature			°C		
Max. mould temperature		110	°C		
Characteristics					
Processing	Injection Moulding				
Delivery form	Pellets				
Additives	Release agent, Flame retardant				

Flame retardant, Lead-free soldering resistant

Additional information

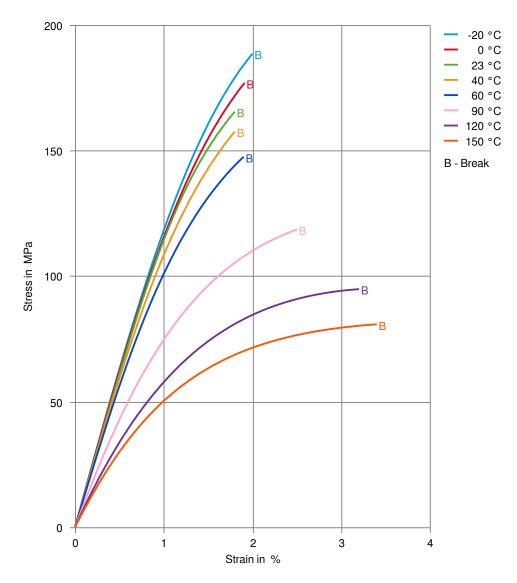
Special characteristics

Injection molding

During molding, use proper protective equipment and adequate ventilation. Avoid exposure to fumes and limit the holdup time and temperature of the resin in the machine. Purge degraded resin carefully with HDPE.

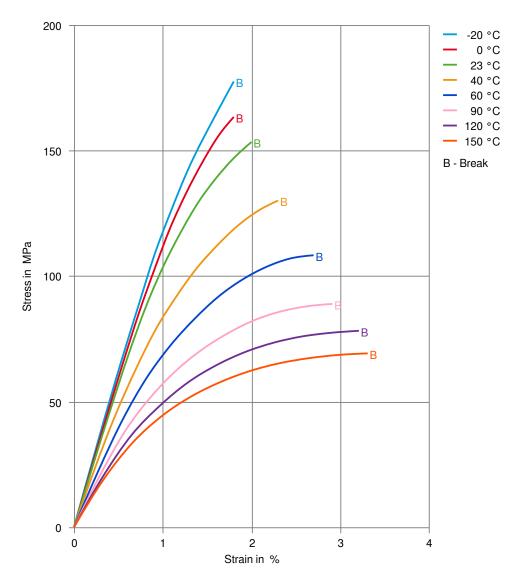


Stress-strain (dry)



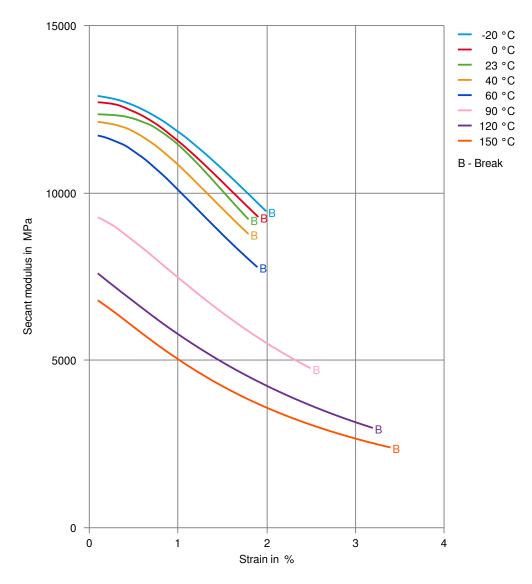


Stress-strain (cond.)



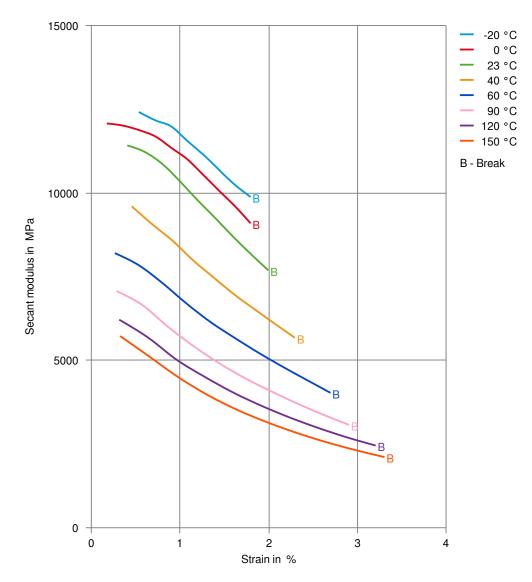


Secant modulus-strain (dry)





Secant modulus-strain (cond.)



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